

PCN Number:	20160331000		PCN Date:	03/31/2016	
Title:	INA333 Die Revision Change				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	07/01/2016	Estimated Sample Availability:	Date provided at sample request.		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
<p>This notification is to inform of a die revision change to select devices. A metal change was performed in order to correct noise issues observed at different temperatures and power supply levels. The design change does not affect the form fit or function of the device. There will be no accompanying changes to the device specifications. The design changes do not affect the device's guaranteed datasheet specifications or electrical performance.</p> <p>Affected devices are listed in the product affected section of this document.</p>					
Reason for Change:					
Improved product performance					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Die Rev designator will change as shown in the table and sample label below:					
Current	New				
Die Rev [2P]	Die Rev [2P]				
E	F				
Sample product shipping label (not actual product label)					
Product Affected:					
INA333-W	INA333SHKQ	INA333SKGD1	INA333SKGD2		
INA333SHKJ	INA333SJD				

Qualification Report

INA333 rev F die
Approved 10/30/2014

Product Attributes

Attributes	Qual Device: INA333AIDRGR	QBS Product: INA333AIDRG	QBS Process: OPA300AID	QBS Package: BQ24703RHD	QBS Package: BUF07704AIPWP	QBS Package: SN75DP139RGZ	QBS Package: TPA5050RSA	QBS Package: TPS51427ARHB	QBS Package: TPS51620RHAR
Assembly Site	MLA	MLA	CRS	MLA	MLA	MLA	MLA	MLA	MLA
Package Family	WSON	WSON	SOIC	VQFN	HTSSOP	VQFN	VQFN	VQFN	VQFN
Wafer Fab Site	DMOS5	DMOS5	DMOS5	DFAB	DMOS5	FFAB	DMOS5	MIHO8	DFAB
Wafer Fab Process	50HPA07	50HPA07	50HPA07	LBC4X	50HPA07X3	BICOM3XL	1833C05X4	LBC7	LBC4X

- QBS: Qual By Similarity
- Qual Device INA333AIDRGR is qualified at LEVEL2-260CG
- Device VSP6825AZRCR contains multiple dies.

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: INA333AIDRGR	QBS Product: INA333AIDRG	QBS Process: OPA300AID	QBS Package: BQ24703RHD	QBS Package: BUF07704AIPWP	QBS Package: SN75DP139RGZ	QBS Package: TPA5050RSA	QBS Package: TPS51427ARHB	QBS Package: TPS51620RHAR
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	-	-	-	-	-
AC	Autoclave 121C	96 Hours	-	1/77/0	3/231/0	1/77/0	3/231/0	1/77/0	3/230/0	3/231/0	3/231/0
TC	**T/C -65C/150C (1000 Cyc)	-85C/+150C (1000 Cyc)	-	-	-	-	-	-	-	-	-
TC	Temperature Cycle -65/150C	600 Cycles	-	1/77/0	3/231/0	1/77/0	3/231/0	1/77/0	2/154/0	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	3/135/0	-	-	-	-	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	1/77/0	3/231/0	1/77/0	3/231/0	3/231/0	3/230/0
TS	Thermal Shock -65/150C	600 Cycles	-	-	-	1/76/0	3/231/0	1/77/0	3/231/0	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	4/464/0	-	-	-	-	-	-
HBM	ESD HBM	4000 V	-	1/3/0	1/3/0	-	-	-	-	-	-
CDM	ESD - CDM	1000 V	-	1/3/0	1/3/0	-	-	-	-	-	-
LU	Latch-up (per JESD78)	-	-	1/6/0	1/12/0	-	-	-	-	-	-
ED	Electrical Characterization Per Datasheet Parameters	-	2/Pass	1/Pass	1/Pass	-	-	-	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -85C/125C/700 Cycles and -85C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
 Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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